



Dear Valued Customer

Doc. No.: 2222002
Issue date: September 1, 2022

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ROHM Co., Ltd.

Notification of Product/Process Change

This is an announcement of change(s) to the process of the products currently supplied by ROHM Co., Ltd.

We request your acknowledgement of the receipt of this notification within the given period.

Please provide your reply by September 1, 2023

Title of change	Wafer Diameter Change, Wafer Process Production Site Change for 3rd Generation SiC MOSFET (TO247N Package) SCT3****L Series [PCN No.2222002]		
Affected product(s)	Manufacturer part number		Customer part number
	SCT3□□□□LGC11/SCT3□□□□LHRC11		
Detailed description of change	Now		After
	<ul style="list-style-type: none"> On-board SiC chip's wafer diameter:4inch Front-end manufacturing plants : ROHM Apollo Co., Ltd. Chikugo Plant 		<ul style="list-style-type: none"> On-board SiC chip's wafer diameter:6inch Front-end manufacturing plants : Lapis Semiconductor Co., Ltd. Miyazaki Plant
Reason for change	To expand production capacity.		
Anticipated impact on quality	There is no difference in reliability and electrical characteristics.		
Identification of change	It can be identified by Lot number.		
Planned first ship date :	April 1, 2023	Sample available schedule :	Within 1.5 months from request
Attachments (data, report)	yes	4M 2222002-2_4ME	Rbl 2222002-3_Rbl
Comments			

	Reply date	
Customer reply	<input type="checkbox"/> 1. Approved. <input type="checkbox"/> 2. Accepted with conditions. <input type="checkbox"/> 3. Rejected.	
Condition for approval / reason for rejection		
Comments		
Customer company name		
Customer signature	Department	
Customer signature	Department	